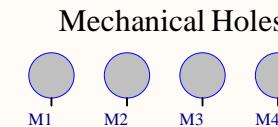
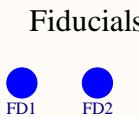


Rev	Description	Date	Author
1.0	Initial Release.	01/07/20	Yan C. de Azeredo

### Revision History



### PCB Elements

#### Semi USB Interstage Interface Panels of FloripaSat-2 2U CubeSat

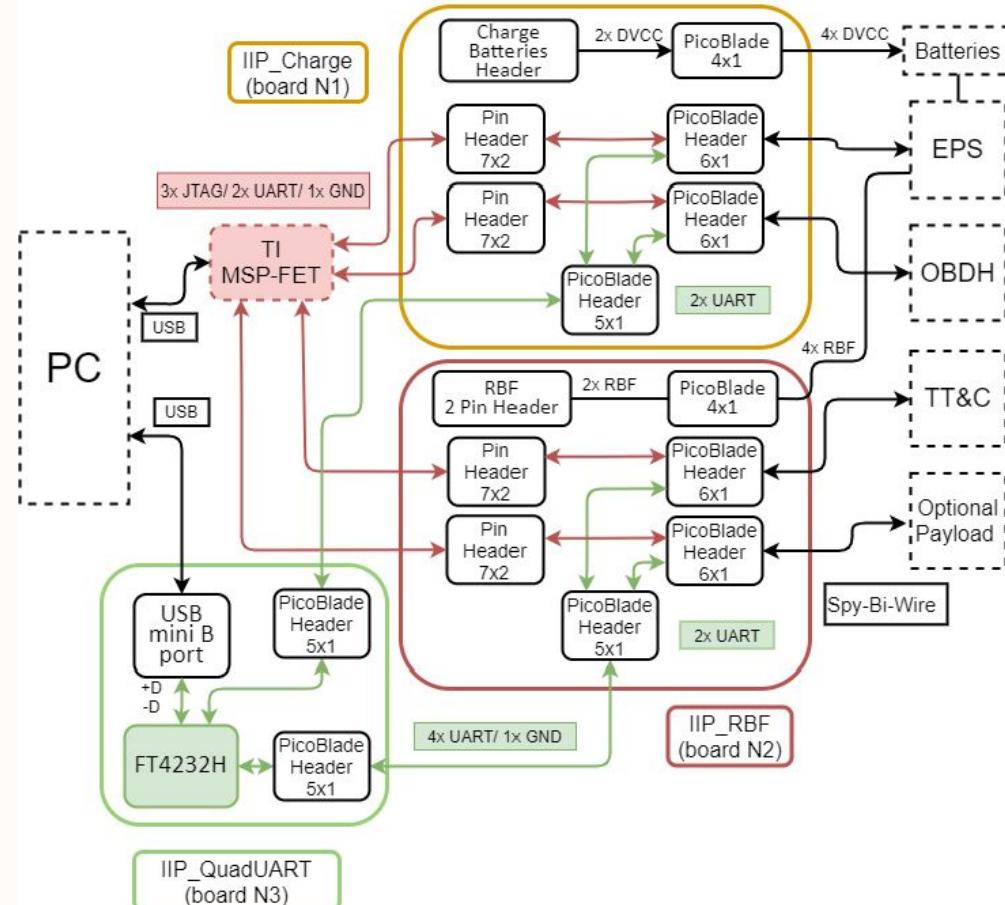
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- Drawn by: Yan Castro de Azeredo
- Reviewers: Gabriel M. Marcelino and André M. P. Mattos
- Support: Gabriel M. Marcelino, André M. P. Mattos and Kleber Gouveia
- Mechanical validation: Edemar Morsch Filho

### Project Information

## Semi USB Interstage Interface Panels



## Full System Block Diagram

SpaceLab - Federal University of Santa Catarina	+	+
Project: <a href="#">2_iip_rbf.PnjPCB/[No Variations]</a>	+	+
Title: <a href="#">IIP Hardware Architecture</a>	+	+
Designed by: <a href="#">Yan Castro de Azeredo</a>	+	Project Code: <a href="#">IIP</a>
Date: <a href="#">11/29/2020</a>	Revision: <a href="#">1.0</a>	Sheet <a href="#">1</a> of <a href="#">2</a>
		Size: <a href="#">A4</a>

A

B

C

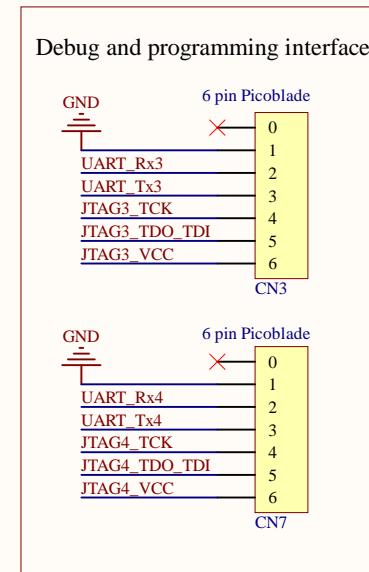
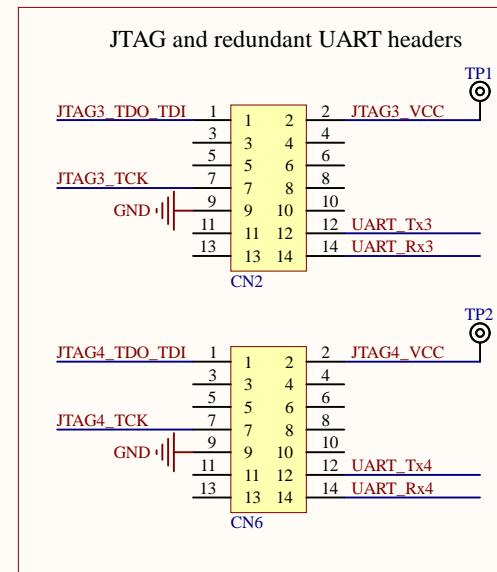
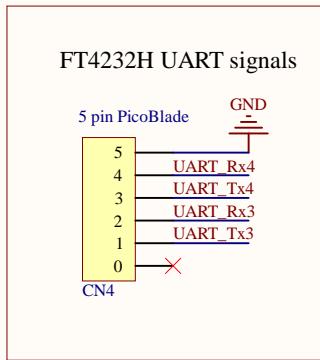
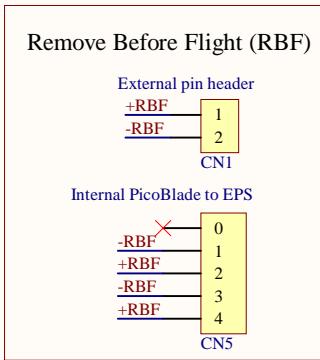
D

A

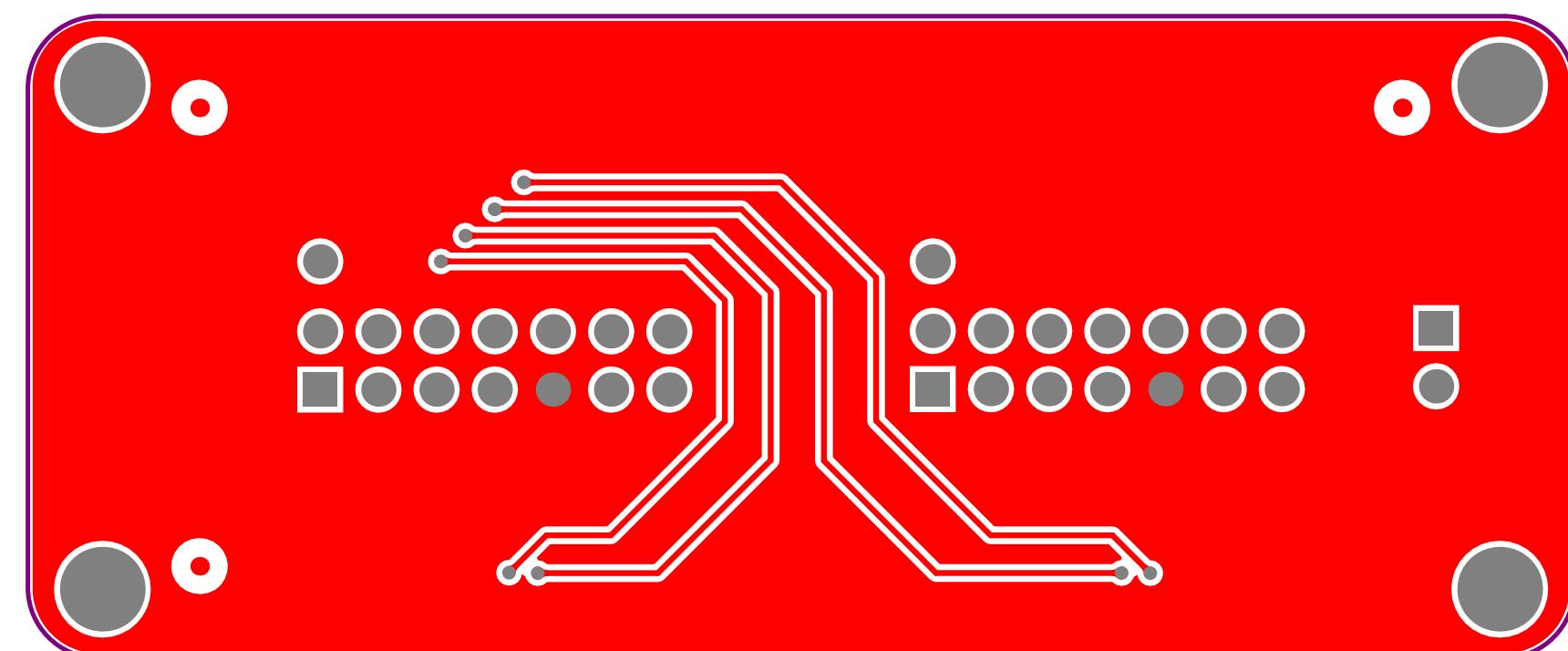
B

C

D

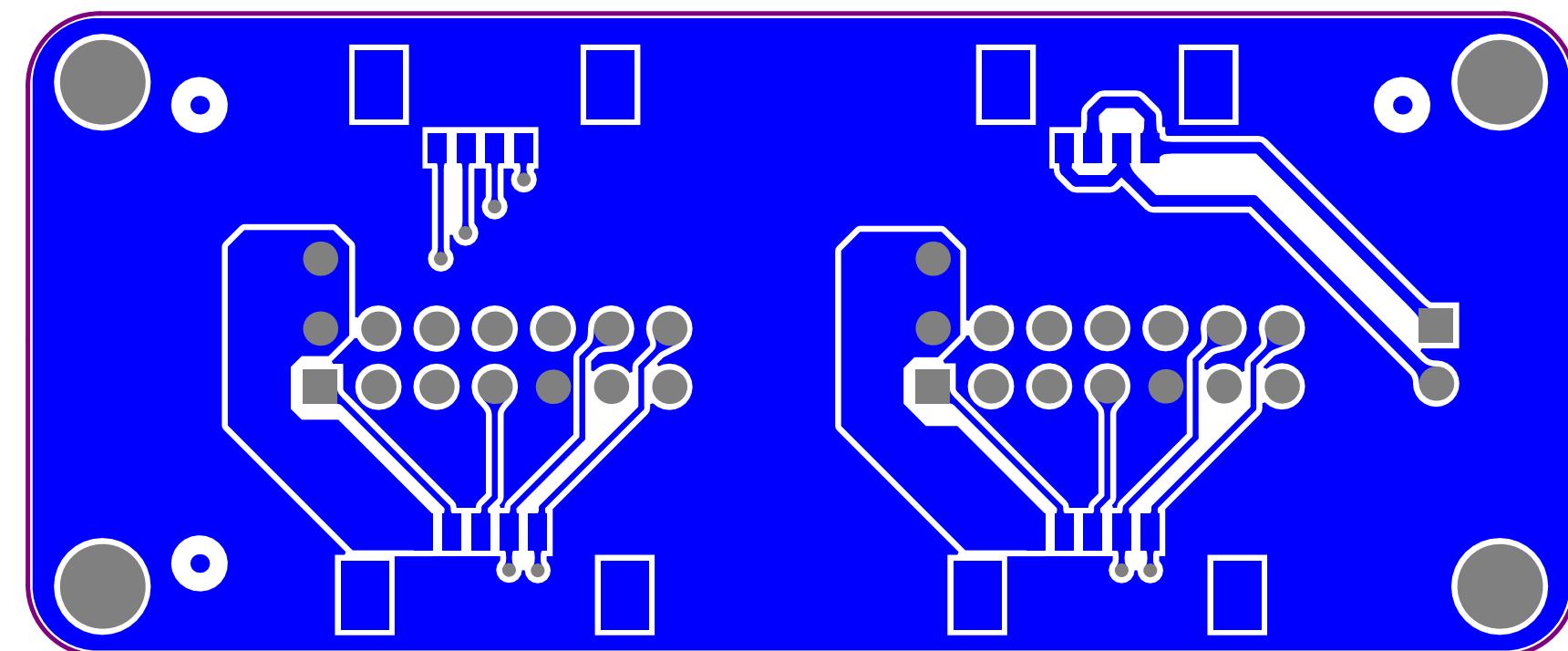


Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.010mm	3.5	
1	Top Layer	Copper	0.036mm		
	Dielectric 1	FR-4	1.500mm	4.8	
2	Bottom Layer	Copper	0.036mm		
	Bottom Solder	Solder Resist	0.010mm	3.5	
	Bottom Overlay				



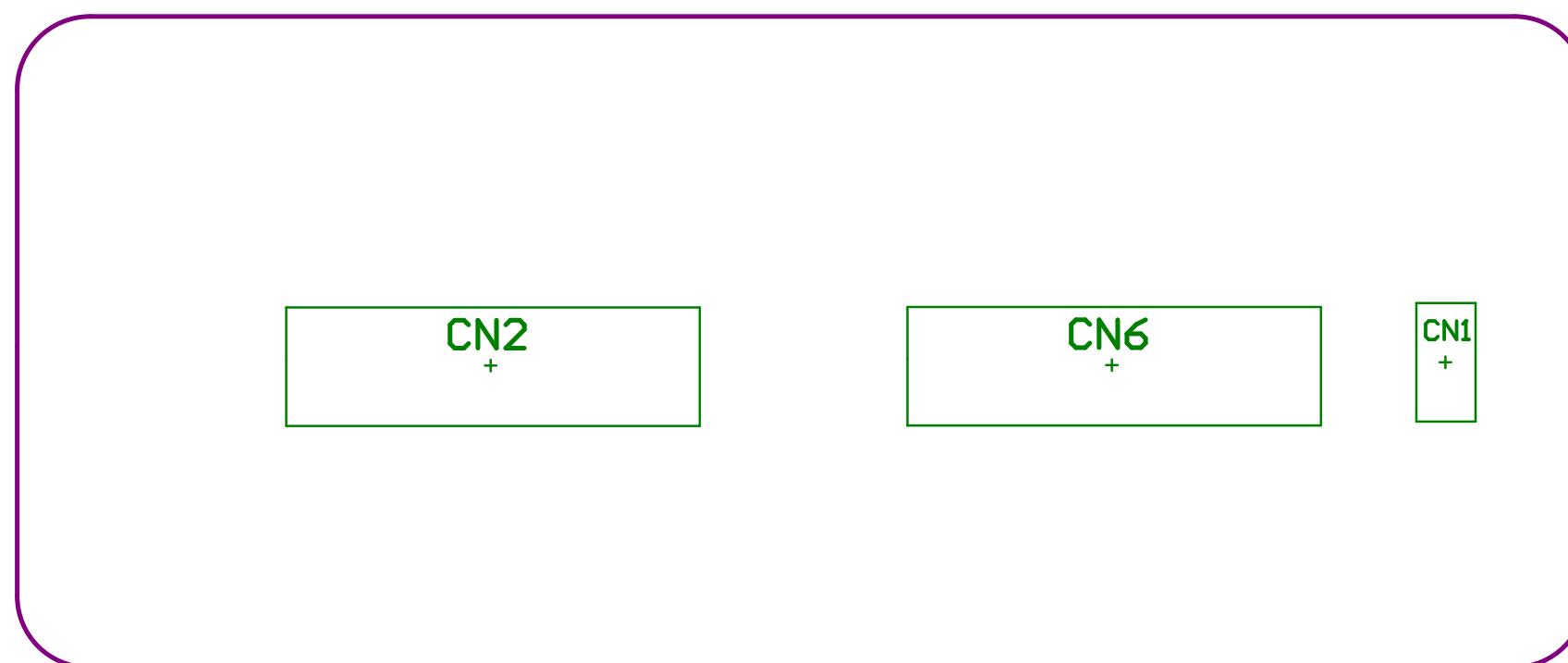
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<b>MATERIAL:</b> FR4		<b>Silkscreen color:</b> white	<b>Project:</b> IIP
<b>Board Thickness:</b> 1.6mm	<b>Layers:</b> 02		Space Technology Research Laboratory Federal University of Santa Catarina SpaceLab UFSC
<b>PCB Surface:</b> HASL	<b>Drawing:</b> Yan C. de Azeredo		

Layer	Name	Material	Thickness	Constant	Board Layer Stack
	Top Overlay				
	Top Solder	Solder Resist	0.010mm	3.5	
1	Top Layer	Copper	0.036mm		
	Dielectric 1	FR-4	1.500mm	4.8	
2	Bottom Layer	Copper	0.036mm		
	Bottom Solder	Solder Resist	0.010mm	3.5	
	Bottom Overlay				



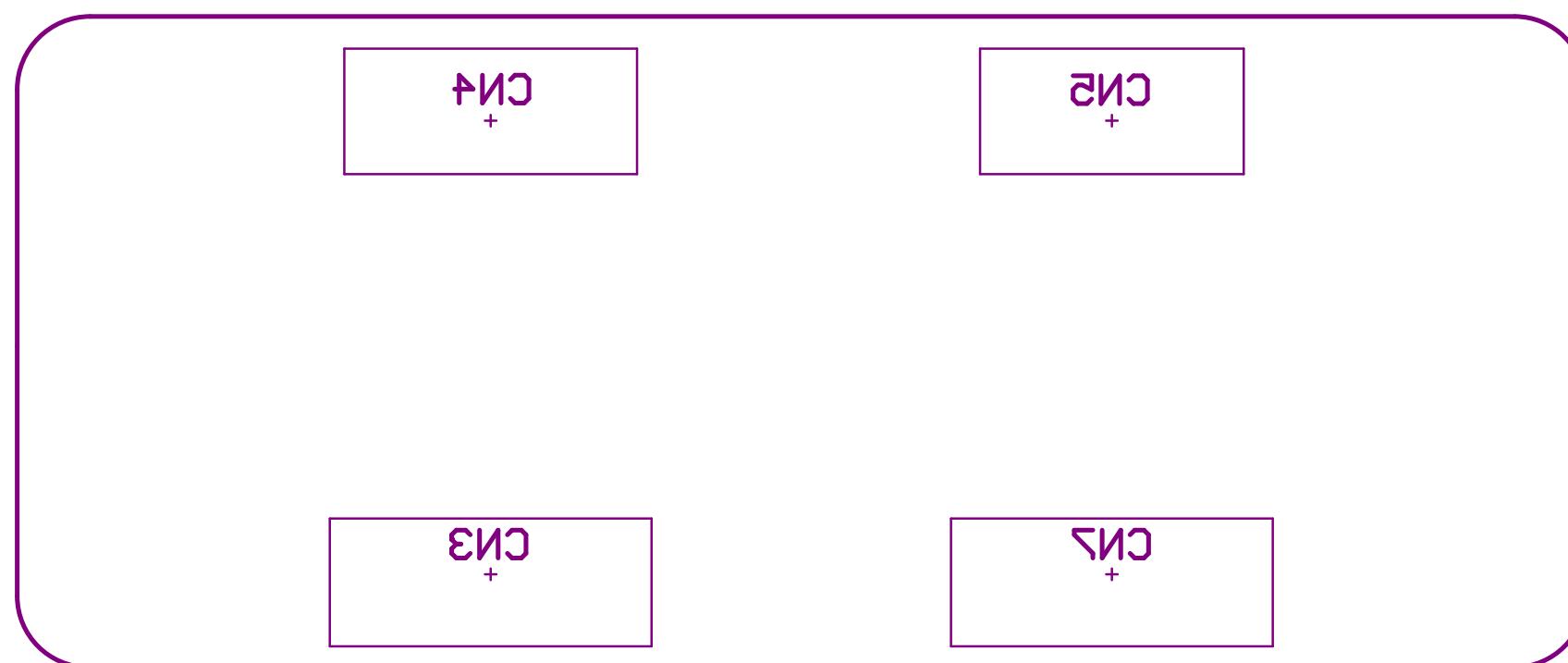
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<b>MATERIAL:</b> FR4		<b>Silkscreen color:</b> white	<b>Project:</b> IIP
<b>Board Thickness:</b> 1.6mm		<b>Layers:</b> 02	Space Technology Research Laboratory Federal University of Santa Catarina SpaceLab UFSC
<b>PCB Surface:</b> HASL		<b>Drawing:</b> Yan C. de Azeredo	

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	Bottom Solder	Solder Resist	0.010mm	3.5	
	Bottom Overlay				



<b>TITLE:</b> IIP N.2 BOARD RBF		<b>REV:</b> 1.0	<b>DATE:</b> 02/07/2020
<b>MATERIAL:</b> FR4		<b>Silkscreen color:</b> white	<b>Project:</b> IIP
<b>Board Thickness:</b> 1.6mm		<b>Layers:</b> 02	Space Technology Research Laboratory Federal University of Santa Catarina SpaceLab UFSC
<b>PCB Surface:</b> HASL		<b>Drawing:</b> Yan C. de Azeredo	

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<b>TITLE:</b> IIP N.2 BOARD RBF		<b>REV:</b> 1.0	<b>DATE:</b> 02/07/2020
<b>MATERIAL:</b> FR4		<b>Silkscreen color:</b> white	<b>Project:</b> IIP
<b>Board Thickness:</b> 1.6mm		<b>Layers:</b> 02	Space Technology Research Laboratory Federal University of Santa Catarina SpaceLab UFSC
<b>PCB Surface:</b> HASL		<b>Drawing:</b> Yan C. de Azeredo	



## Bill of Materials

Source Data From: 2\_iip\_rbf.PrjPCB

Project: 2\_iip\_rbf.PrjPCB

Variant: None

Project Code: IIPN2

Report Date: 11/29/2020

11:17 PM

Print Date: 29/11/2020

23:17:22

#	Designator	Quantity	Manufacturer	Manufacturer Part Number	#Column Name Error:' Partnumber	Description	#Column Name Error:' P	Footprint	Mount	Fitted
1	CN3, CN7	2	Molex	53398-0671		1.25mm Pitch PicoBlade™ Header, Surface Mount, Vertical, 6 Circuits		PICO BLADE 0533980671	Surface Mount	Fitted
2	CN2, CN6	2	Harwin	M20-9980745		Headers & Wire Housings 07+07 DIL VERTICAL PIN HEADER GOLD HT		CONN HEADER VERT 14POS 2.54MM	Through Hole	Fitted
3	CN5	1	Molex	53398-0471		Connector Header Surface Mount 4 position 0.049" (1.25mm)		PICO BLADE 0533980471	Surface Mount	Fitted
4	CN4	1	Molex	53398-0571		Wire-To-Board Connector, Vertical, PicoBlade 53398 Series, Surface Mount, Header, 5, 1.25 mm		PICO BLADE 0533980571	Surface Mount	Fitted
5	CN1	1	Harwin	M20-9990245		M20 HDR, PIN, SIL, VERT, 2W		CONN HEADER VERT 2POS 2.54mm	Through Hole	Fitted